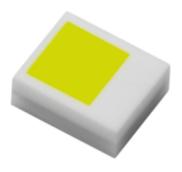


## **DATASHEET**

## EL Compact 2016 CH2016-C07001H-AM



#### **Features**

· Package: Cool White LEDs on Ceramic substrate

Typ. Color Temperature: 5180 K ~ 6680 K

Typ. Luminous Flux: 195 lm @ 700mA

Viewing angle : Cold White 120°

ESD: up to 8KV

• MSL:1

Preconditioning: According to JEDEC J-STD 020D Level 1

Qualifications : According to AEC-Q101

Compliance with RoHS and REACH

### **Applications**

· Automotive Exterior Lighting, Day Time Running Light (DRL), Tail Light



# **Contents**

1.	Characteristics	3
2.	Absolute Maximum Ratings	4
3.	Characteristics Graph	5
4.	Binning Information	10
5.	Part Number	15
6.	Ordering Information	16
7.	Mechanical Dimension	17
8.	Recommended Soldering Pad	18
9.	Reflow Soldering Profile	18
10	Packaging Information	19
11.	Handling of Silicon Resin for LEDs	<b>2</b> 1
12	Precaution for Use	22



## 1. Characteristics

Paramet	er	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Cu	rrent	I <sub>F</sub>	50	700	800	mA	
Luminous Flu	IX <sup>[1][2][3]</sup>	Ф	150	195	275	lm	I <sub>F</sub> =700mA
Forward Volta	age <sup>[4][5]</sup>	$V_{F}$	3.00	3.25	3.75	V	I <sub>F</sub> =700mA
Viewing Ar	ngle	φ		120		deg	I <sub>F</sub> =700mA
Correlated Color T	emperature	K	5180	5850	6680	K	I <sub>F</sub> =700mA
Thermal Resistance (Junction to Solder)	Real	R <sub>th JS real</sub>		10.59		K/W	I <sub>F</sub> =700mA
	Electrical	R <sub>th JS el</sub>		7.87		r∨vv	I <sub>F</sub> =700IIIA

- 1. Luminous Flux measurement tolerance: ±8%.
- 2. The data of Luminous Flux measured at thermal pad=25°C
- 3. Typical luminous flux or light output performance is operated within the condition guided by this datasheet.
- 4. Forward voltage measurement tolerance: ±0.05V
- 5. The  $V_{\text{F}}$  range shown in the table above indicates 99% output.
- 6. Tolerance of Chromaticity Coordinates x,y:  $\pm 0.005$



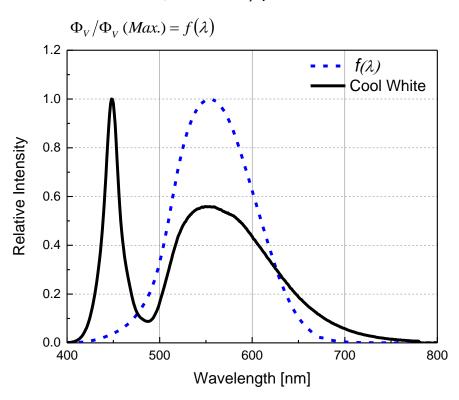
# 2. Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Reverse Voltage	$V_R$	Not designed for reverse operation	V
Power Dissipation	$P_d$	3000	mW
Max. DC Forward Current	I <sub>F</sub>	50 ~ 800	mA
Surge current	I <sub>FM</sub>	2500	mA
Junction Temperature	TJ	150	°C
Operating Temperature	T <sub>opr</sub>	-40 ~ +125	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +125	°C
ESD Sensitivity	ESD <sub>HBM</sub>	8	kV
Soldering Temperature	Reflow	260°C for 30 sec	°C



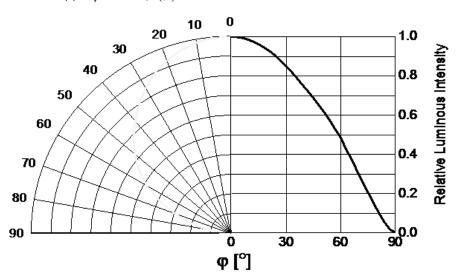
# 3. Characteristics Graph

# Wavelength Characteristics Relative Spectral Distribution @ Ts = 25°C, I<sub>F</sub>=700mA



## **Typical Diagram Characteristics of Radiation**

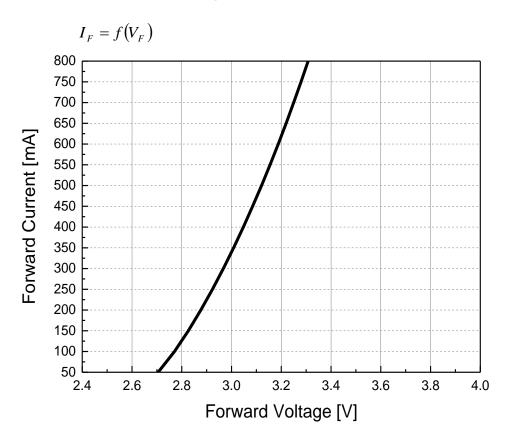
$$\Phi_V/\Phi_V(0^\circ) = f(\varphi)$$



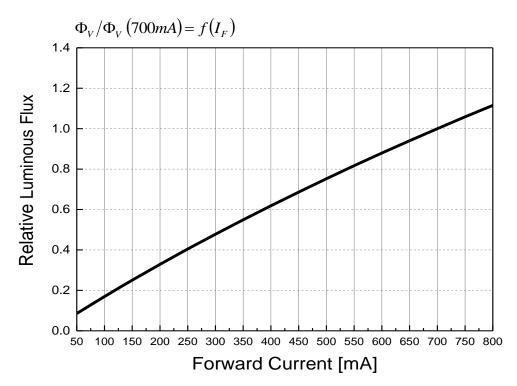
- 1.  $\varphi$  is the off axis angle from lamp centerline where the luminous intensity is 1/2 of the peak value.
- 2. View angle tolerance is ± 5°.



#### Forward Current vs. Forward Voltage @ Ts = 25°C

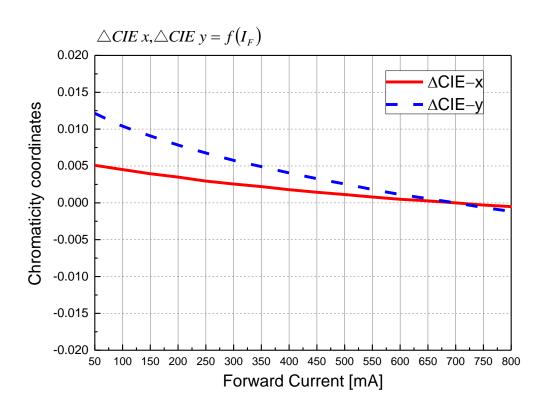


#### Relative Luminous Flux vs. Forward Current @ Ts = 25°C

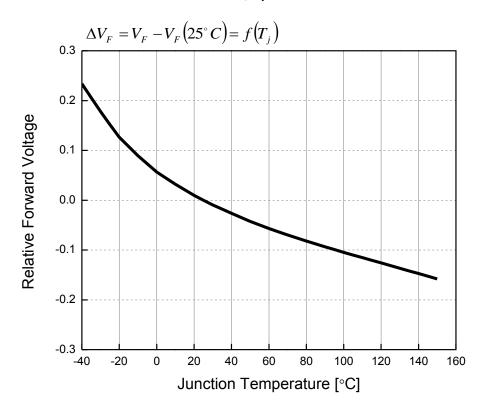




# Chromaticity Coordinates Shift vs. Forward Current @ Ts = 25°C

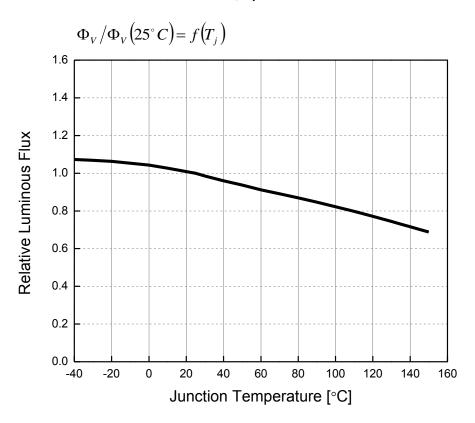


# Relative Forward Voltage vs. Junction Temperature @ I<sub>F</sub>=700mA

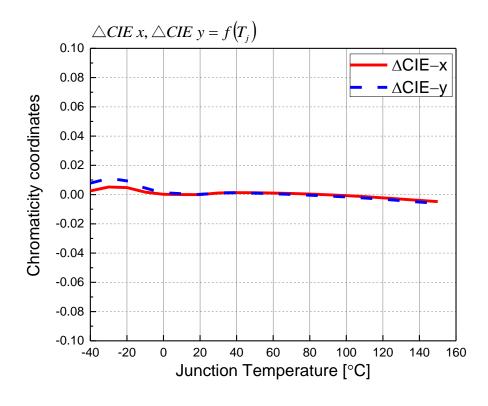




# Relative Luminous Flux vs. Junction Temperature @ I<sub>F</sub>=700mA

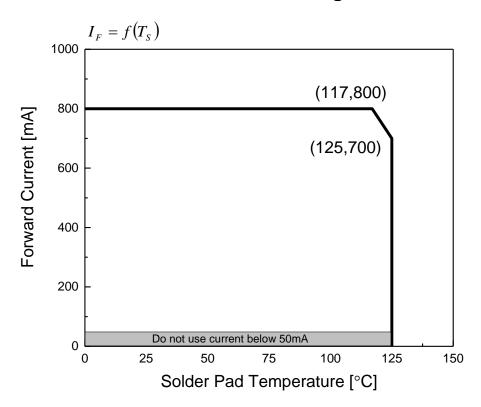


# Chromaticity Coordinates Shift vs. Junction Temperature @ I<sub>F</sub>=700mA

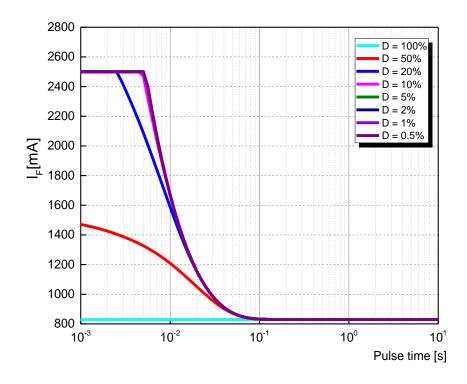




### **Forward Current Derating Curve**



# **Permissible Pulse Handling Capability** D=Duty cycle , T<sub>s</sub> = 25C





# 4. Binning Information

## **Luminous Intensity Bins**

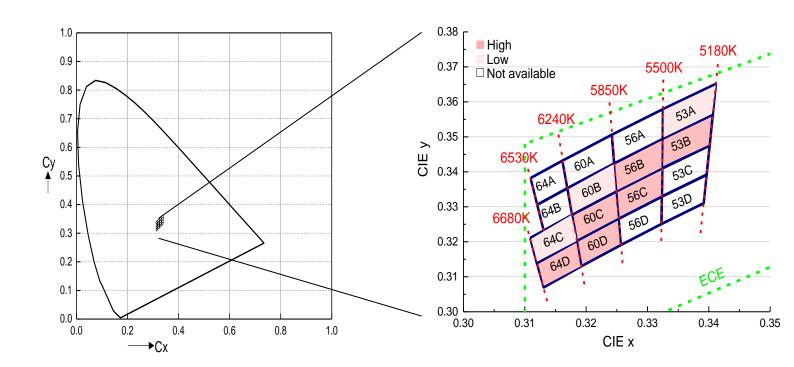
Group	Bin	Minimum Photometric Flux (Im)	Maximum Photometric Flux (Im)
	1	4	5
	2	5	6
	3	6	8
	4	8	10
E	5	10	13
	6	13	17
	7	17	20
	8	20	23
	9	23	27
	1	27	33
	2	33	39
	3	39	45
	4	45	52
F	5	52	60
	6	60	70
	7	70	80
	8	80	90
	9	90	100

Group	Bin	Minimum Photometric Flux (Im)	Maximum Photometric Flux (lm)
	1	100	110
	2	110	120
	3	120	130
	4	130	140
J	5	140	150
	6	150	160
	7	160	180
	8	180	200
	9	200	225
	1	225	250
	2	250	275
	3	275	300
	4	300	325
K	5	325	350
	6	350	375
	7	375	400
	8	400	425
	9	425	450

- 1. Luminous flux measurement tolerance: ±8%.
- 2. Highlighted Black Box is available bins.



# Color Bin Structure ECE White Bin Structure



#### **Cool White Bin Coordinates**

Bin	CIE x	CIE y
64A	0.3109	0.3382
	0.3161	0.3432
	0.3169	0.3353
	0.3120	0.3306
Reference Range: 6240~6530K		

Bin	CIE x	CIE y
	0.3120	0.3306
640	0.3169	0.3353
64B	0.3177	0.3277
	0.3131	0.3232
Reference Range: 6240~6530K		

Bin	CIE x	CIE y
	0.3109	0.3211
64C	0.3177	0.3277
640	0.3185	0.3203
	0.3120	0.3139
Reference Range: 6240~6680K		

Bin	CIE x	CIE y
0.45	0.3120	0.3139
	0.3185	0.3203
64D	0.3192	0.3131
	0.3131	0.3070
Reference Range: 6240~6680K		



### **Cool White Bin Coordinates**

Bin	CIE x	CIE y
	0.3161	0.3432
604	0.3242	0.3506
60A	0.3246	0.3424
	0.3169	0.3353
Reference Range: 5850~6240K		

Bin	CIE x	CIE y
005	0.3169	0.3353
	0.3246	0.3424
60B	0.3249	0.3344
	0.3177	0.3277
Reference Range: 5850~6240K		

Bin	CIE x	CIE y
	0.3177	0.3277
60C	0.3249	0.3344
60C	0.3253	0.3266
	0.3185	0.3203
Reference Range: 5850~6240K		

Bin	CIE x	CIE y
	0.3185	0.3203
60D	0.3253	0.3266
600	0.3256	0.3191
	0.3192	0.3131
Reference Range: 5850~6240K		

Bin	CIE x	CIE y
504	0.3242	0.3506
	0.3325	0.3579
56A	0.3325	0.3493
	0.3246	0.3424
Reference Range: 5500~5850K		

Bin	CIE x	CIE y
500	0.3246	0.3424
	0.3325	0.3493
56B	0.3324	0.3410
	0.3249	0.3344
Reference Range: 5500~5850K		

Bin	CIE x	CIE y
500	0.3249	0.3344
	0.3324	0.3410
56C	0.3323	0.3329
	0.3253	0.3266
Reference Range: 5500~5850K		

Bin	CIE x	CIE y
56D	0.3253	0.3266
	0.3323	0.3329
	0.3323	0.3251
	0.3256	0.3191
Reference Range: 5500~5850K		

Bin	CIE x	CIE y
504	0.3325	0.3579
	0.3412	0.3652
53A	0.3406	0.3562
	0.3325	0.3493
Reference Range: 5180~5500K		

Bin	CIE x	CIE y
	0.3325	0.3493
EOD	0.3406	0.3562
53B	0.3401	0.3476
	0.3324	0.3410
Reference Range: 5180~5500K		



#### **Cool White Bin Coordinates**

Bin	CIE x	CIE y
	0.3324	0.3410
53C	0.3401	0.3476
530	0.3396	0.3392
	0.3323	0.3329
Reference Range: 5180~5500K		

Bin	CIE x	CIE y
500	0.3323	0.3329
	0.3396	0.3392
53D	0.3392	0.3310
	0.3323	0.3251
Reference Range: 5180~5500K		

#### Notes:

1. Tolerance of Chromaticity Coordinates x,y: ±0.005



## **Forward Voltage Bins**

Bin code	Forward Voltage [V]
10	1.00
12	1.25
15	1.50
17	1.75
20	2.00
22	2.25
25	2.50
27	2.75
30	3.00
32	3.25
35	3.50
37	3.75
40	4.00
42	4.25
45	4.50
47	4.75
50	5.00
52	5.25
55	5.50
57	5.75
60	6.00
62	6.25
65	6.50
67	6.75
70	7.00

- 1. Bin code defines either Minimum or Maximum Value of the Bin.
- 2. Forward voltage measurement tolerance: ±0.05V.
- 3. Forward voltage bins are defined at  $I_F$  = 700mA operation.
- 4. Highlighted Black Box is available bins.



## 5. Part Number

### CH2016-C07001H-AM

Part number is designated with below details.

CH2016 = Product family name.

C = Color [1]

0 = CRI (0=N/A; >70%=7; >80%=8; >90%=9)

700 = Test current [mA]

1 = Metallic Plating Type ( 0=Ag; 1=Au)

H = Brightness Level (H=High; L=Low)

AM = automotive application

Note

<sup>[1]</sup> Color :

Symbol	Description
С	Cool White
N	Neutral White
W	Warm White
PA	Phosphor Converted Amber
PR	Phosphor Converted Red
UB	Blue
IB	Ice Blue
SB	Sky Blue
UG	Green
UY	Yellow
UA	Amber
UR	Red
SR	Super Red
RGB	RGB – Color
RGBY	RGBY – Color



# 6. Ordering Information

### CH2016-C07001H-ABCDEFGHJKLMNO-PQ-AM

Part Number of the EL Compact 2016	Order Code
CH2016-C07001H-AM	CH2016-C07001H-53A64DJ6K23037-2T-AM

Order code contains information with below details:

ABCDEF = min/max wavelength or CCT

GHJK = min./max. luminous flux in [lm] or luminous intensity in [mcd]

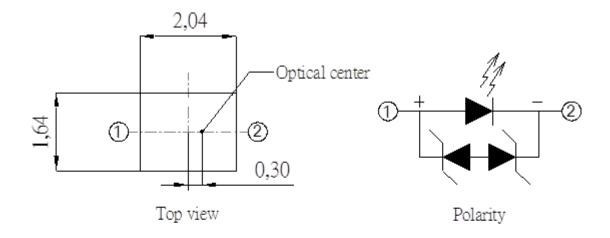
LMNO = min./max. forward voltage

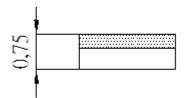
PQ =Internal code

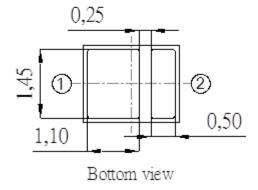
AM = Automotive Application



## 7. Mechanical Dimension



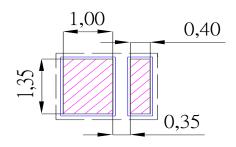




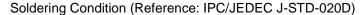
- 1. Dimensions are in millimeters.
- 2. Tolerances unless mentioned are ± 0.1mm.

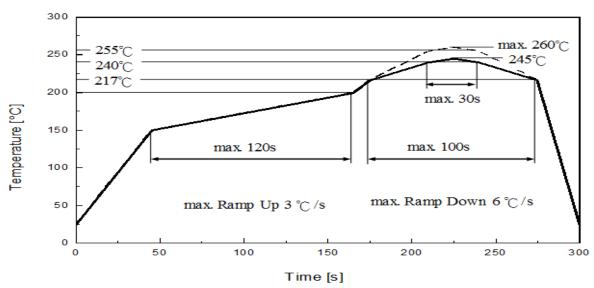


## 8. Recommended Soldering Pad



## 9. Reflow Soldering Profile



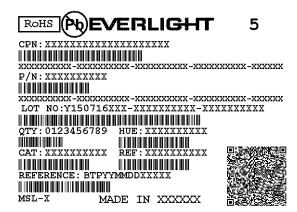


**Pb-Free Assembly Profile Feature Unit Einheit** Recommendation Ramp-up rate to preheat 3 °C /sec 25 °C to 150 °C Time of soaking zone 120 sec 150 °C to 200 °C Ramp-up rate to peak 3 °C /sec Liquidus temperature 217 °C Time above liquidus temperature 100 sec Peak temperature (max.) 260 °C Time within 5°C of the specified peak 30 sec temperature Ramp-down Rate (max.) 6 °C /sec



## 10. Packaging Information

### • Product Labeling



· CPN: Customer's Product Number

• P/N : Everlight Part Number

QTY : Packing Quantity

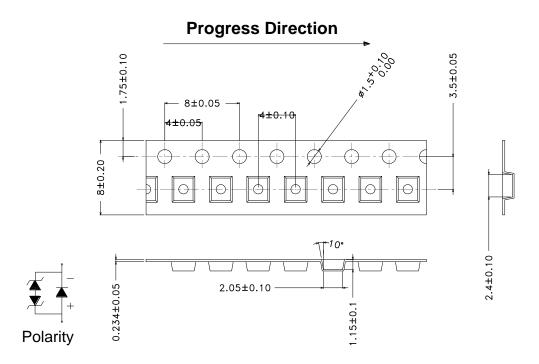
· CAT: Luminous Flux (Brightness) Bin

• HUE: Color Bin

• REF : Forward Voltage Bin

· LOT No: Lot Number

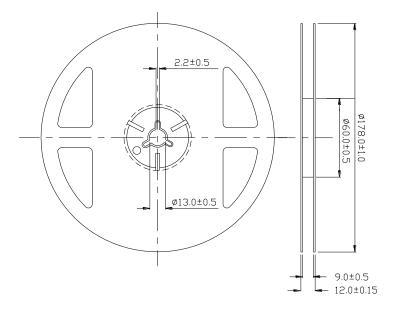
### • Packing: Loaded Quantity 2000 pcs Per Reel



- 1. Dimensions are in millimeters.
- 2. Tolerances for fixed dimensions are ±0.2mm.



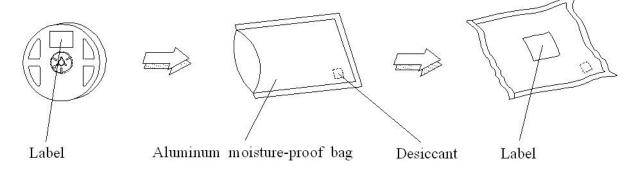
#### Reel Dimensions



#### Notes:

- 1. Dimensions are in millimeters.
- 2. Tolerances unless mentioned are ±0.2mm.

### • Moisture Resistant Packing Process

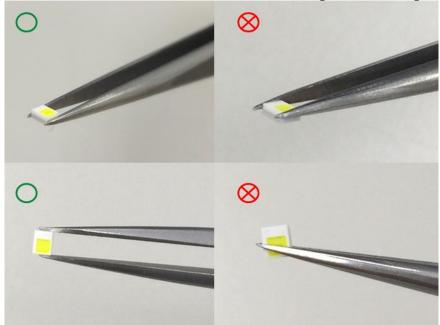


- 1. Dimensions are in millimeters.
- 2. Tolerances unless mentioned are ±0.2mm.



# 11. Handling of Silicon Resin for LEDs

- Do not put mechanical stress on the LED.
- When handling the product, do not apply direct pressure on the optical surface. The LED surface could be damaged, which could affect the optical performance of the LED.
- In low-humidity work environment, please keep handling the LEDs with appropriate ESD grounding.
- It is recommended to handle the LED with powder-less latex gloves.
- Do not touch the resin with tweezers to avoid scratching or other damage.





### 12. Precaution for Use

- Before the package is opened, the LEDs should be stored at 30°C or less and 90%RH or less after being shipped from Everlight and the storage life limits are 18 months. The LEDs can be stored up to 3 years in a sealed container with a nitrogen atmosphere and moisture absorbent material.
- After opening the package, all unused LEDs are recommended to be stored in moisture proof packages.
- If the moisture absorbent material (silica gel) has exceeded effectiveness or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 60±5°C for 24 hours.



# **Revision History**

Current version: Mar.24.2017

Issue No: DHE-0003225

Version: 2

Created by: Sam Lu

Rev.	Subjects (major change in previous version)	Modified date
1	Mass Production	2016/12/26
2	Add Characteristics Forward Current	2017/03/24